**Draft for Public Comment**

Form 36

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Project No. 2024/00787

Responsible committee: EPL/501 Electronic Assembly Technology

Interested committees:

| | |
|---|---|
| Title: | BS EN IEC 61189-3-302 Test methods for electrical materials, printed board and other interconnection structures and assemblies<br><br>Part 3-302:-detection of plating defects in unpopulated circuit boards by computed tomography (CT) |

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ii) affects other national standard(s)
iii) requires additional national guidance or information

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**Introduction**

This draft standard is based on national and international discussions. Your comments on this draft are invited and will assist in the preparation of the consequent standard.

For international standards, comments will be reviewed by the relevant UK national committee before sending the consensus UK vote and comments to the international committee, which will then decide appropriate action. If the international standard is approved, it is usual for the text to be published as a British Standard.

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**UK Vote**

Please indicate whether you consider the UK should submit a negative (with supporting technical reasons) or positive vote on this draft. Please indicate if you are aware of any reason why this draft standard should not be published as a British Standard.

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**Template for comments and secretariat observations**

| Date: xx/xx/20xx | Document: ISO/DIS xxxx |
|---|---|

| 1 | 2 | (3) | 4 | 5 | (6) | 7 |
|---|---|---|---|---|---|---|
| **MB** | Clause No./ Subclause No./Annex **(e.g. 3.1)** | Paragraph/Figure/ Table/Note | **Type of comment** | **Commend (justification for change) by the MB** | **Proposed change by the MB** | **Secretariat observations on each comment submitted** |
| | 3.1 | Definition 1 | ed | Definition is ambiguous and needs clarifying. | Amend to read '...so that the mains connector to which no connection...' | |
| | 6.4 | Paragraph 2 | te | The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK. | Delete reference to UV photometer. | |

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# 91/1941/CD

COMMITTEE DRAFT (CD)

| | |
|---|---|
| PROJECT NUMBER: **IEC 61189-3-302 ED1** | |
| DATE OF CIRCULATION: **2024-03-08** | CLOSING DATE FOR COMMENTS: **2024-05-31** |
| SUPERSEDES DOCUMENTS: **91/1844/NP, 91/1893/RVN** | |

| | |
|---|---|
| IEC TC 91 : ELECTRONICS ASSEMBLY TECHNOLOGY | |
| SECRETARIAT: Japan | SECRETARY: Mr Osamu IKEDA |
| OF INTEREST TO THE FOLLOWING COMMITTEES: | PROPOSED HORIZONTAL STANDARD: ☐ Other TC/SCs are requested to indicate their interest, if any, in this CD to the secretary. |
| FUNCTIONS CONCERNED: ☐ EMC ☐ ENVIRONMENT ☒ QUALITY ASSURANCE ☐ SAFETY | |

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TITLE:

**Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 3-302: Detection of plating defects in unpopulated circuit boards by computed tomography (CT)**

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Document Sharing Hub

Full document details: 24/30488910 DC

# CONTENTS

FOREWORD ..... 4
1. Scope ..... 6
2. 2.Normative references ..... 6
3. Terms and definitions ..... 6
4. Test principle ..... 6
5. Equipment ..... 7
5.1 X-ray CT scanner ..... 7
5.1.1X-ray source system ..... 7
5.1.2 Mechanical Scanning Systems ..... 7
5.1.3 Detector Systems ..... 7
5.1.4 Shielding Facilities ..... 7
5.2 Software Systems ..... 7
6. Test environment ..... 7
7. Test the steps ..... 8
7.1 Equipment Preparation ..... 8
7.2 Sample clamping ..... 8
7.3 Parameter Settings ..... 8
7.3.1 X-ray sources ..... 8
7.3.2 Scanning Methods ..... 8
7.3.3 Scanning the Field of View ..... 8
7.3.4 Number of Frames Scanned ..... 8
7.3.5 Scan Time ..... 8
7.4 Scanning ..... 9
7.5 Image Reconstruction ..... 9
7.5.1 3D Reconstruction ..... 9
7.5.2 Image Quality ..... 9
7.5.3 Visualization ..... 9
7.5.4 Image Analysis and data processing ..... 9
7.5.5 Image Saving ..... 9
8. Reports ..... 9
8.1 Basic Information ..... 9
8.2 Device Information ..... 9
8.3 Sample Information ..... 9
8.4 Sweep Parameters ..... 9
8.5 Measurement results ..... 10
A.1 Typical image of plating voids ..... 11
A.2 Typical image of copper filling defects ..... 11
A.3 Typical image of rough plating ..... 11
A.4 Typical image of nodulation ..... 12
A.5 Typical image of plating folds ..... 12
A.6 Typical image of interlayer coincidence ..... 12
B.1 Void Identification ..... 14
B.1.1 Principle ..... 14
B.1.2 Via ..... 14

AVA Documents
Document Sharing Hub
Full document details: 24/30488910 DC

B.1.3 Fill hole ..... 14
B.2 Statistical analysis ..... 15
B.2.1 Number of voids ..... 15
B.2.2 Calculated the maximum length of the voids/board thickness ratio ..... 15
B.2.3 Calculated filled holes void rate ..... 15
Bibliography ..... 16

Documents
Document Sharing Hub
Full document details: 24/30488910 DC

INTERNATIONAL ELECTROTECHNICAL COMMISSION

# TEST METHODS FOR ELECTRICAL MATERIALS,PRINTED BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES-

## Part 3-302: Detection of plating defects in unpopulated circuit boards by computed tomography (CT)

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International Standard IEC 61189-3 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this International Standard is based on the following documents:

| FDIS | Report on voting |
|---|---|
| XX/XX/FDIS | XX/XX/RVD |

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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